

2N3458 N-Channel JFET

Features

- InterFET [N0032H Geometry](#)
- Low gate leakage: 750fA typical @20V
- Low Ciss: 3pF typical
- Typical gain: 2mS
- High radiation tolerance
- RoHS, REACH, CMR compliant
- Custom test and binning options available
- SMT, TH, and bare die package options
- Edge case SPICE modeling: [InterFET SPICE](#)

InterFET Similar Parts

- 2N4220-1A, 2N4340-1, 2N4867-8-9A,
- IFN105, IFN40,
- J201-2, J230-1, J320
- VCR4N

InterFET Dual Parts

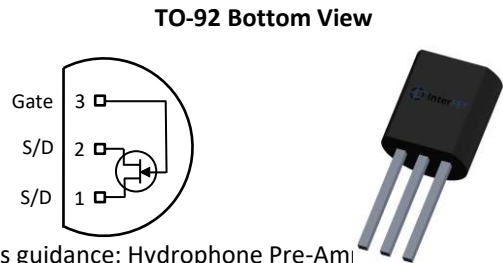
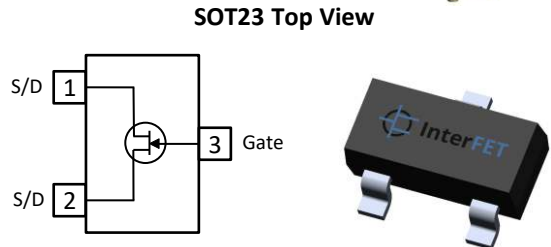
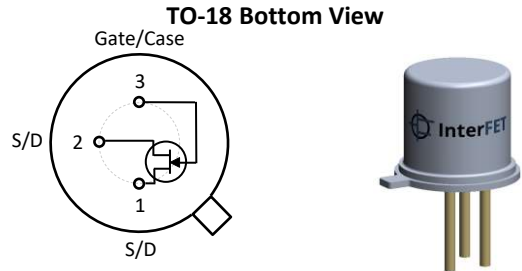
- IFNU401-2-3, IFNU404-5-6, IFN5197-8-9

Applications

- General: Amplifiers; Switches; Voltage regulators; Oscillators; Signal mixers; Noise generators
- Military/Aero: Radar; Communications; Satellites; Missiles guidance; Hydrophone Pre-Amplifier; Sonar; Ultrasound equipment
- Medical: Medical imaging systems; Medical monitors and recorders; Ultrasound equipment
- Audio: Tone control circuits; Headphone amplifiers; Audio filters; Electret Microphone

Description

The -50V InterFET 2N3458, 2N3459, and 2N3460 are targeted for sensitive amplifier stages for mid-frequencies designs. Gate leakages are typically less than 10pA at room temperatures. The 2N3460 has a cutoff voltage of less than 1.8V ideal for low-level power supplies. The TO-18 package is hermetically sealed and suitable for military applications.



Ordering Information Custom Part and Binning Options Available

Part Number	Description	Case	Packaging
2N3458	Through-Hole	TO-18	Bulk
PN3458	Through-Hole	TO-92	Bulk
SMP3458	Surface Mount	SOT23	Bulk
SMP3458	7" Tape and Reel: Max 3,000 Pieces 13" Tape and Reel: Max 9,000 Pieces	SOT23	Minimum 1,000 Pieces Tape and Reel
2N3458COT	Chip Orientated Tray (COT Waffle Pack)	COT	400/Waffle Pack
2N3458CFT	Chip Face-up Tray (CFT Waffle Pack)	CFT	400/Waffle Pack



NOTICE: Please refer to the end of this document for information on product materials, compliance, safety, and legal statements.

Electrical Characteristics

Maximum Ratings (@ $T_A = 25^\circ\text{C}$, Unless otherwise specified)

Parameters	TO-18	SOT-23	TO-92	Unit
V_{RGS} Reverse Gate Source and Gate Drain Voltage	-50	-50	-50	V
I_{FG} Continuous Forward Gate Current	50	50	50	mA
P_D Continuous Device Power Dissipation ¹	500	350	500	mW
P Power Derating ¹	3.3	2.8	4	mW/ $^\circ\text{C}$
T_J Operating Junction Temperature	-65 to 175	-55 to 150	-55 to 150	$^\circ\text{C}$
T_{STG} Storage Temperature	-65 to 175	-55 to 150	-55 to 150	$^\circ\text{C}$

¹ Thermal power dissipation and derating values obtained with gate pin (substrate) thermally connected to pad and/or internal layer.

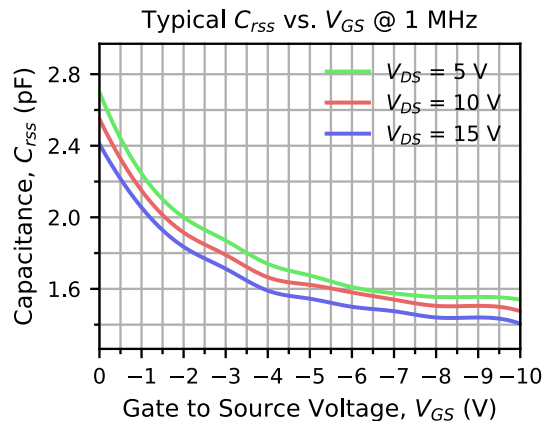
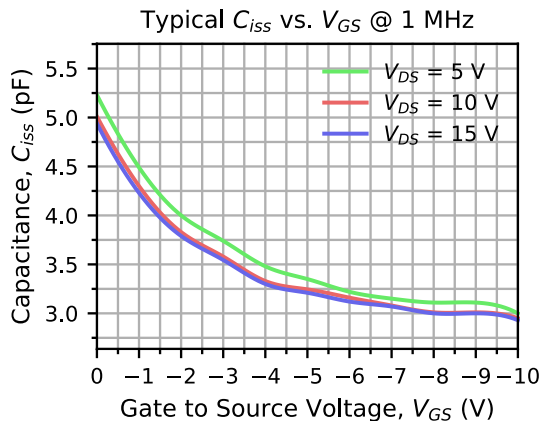
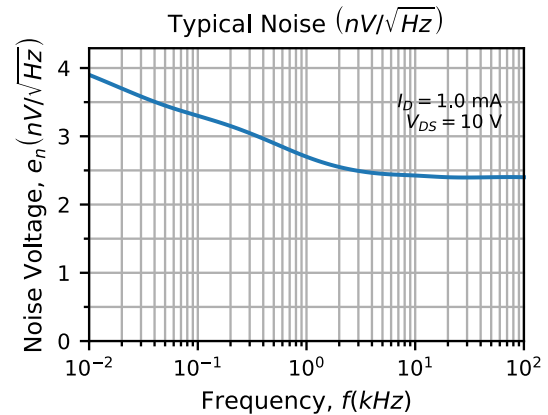
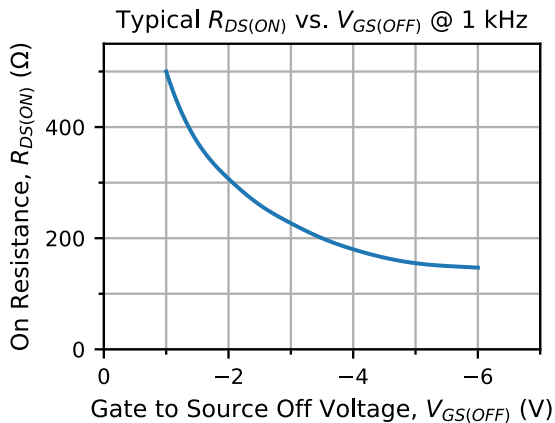
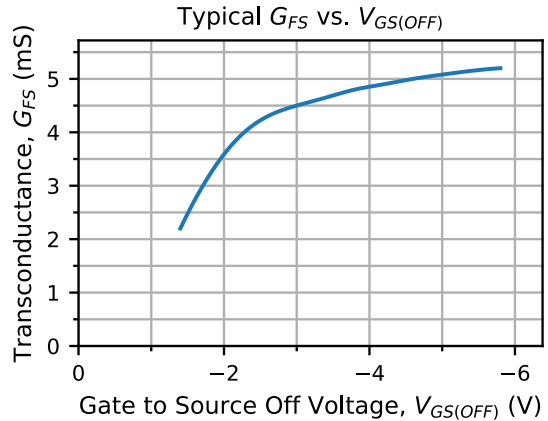
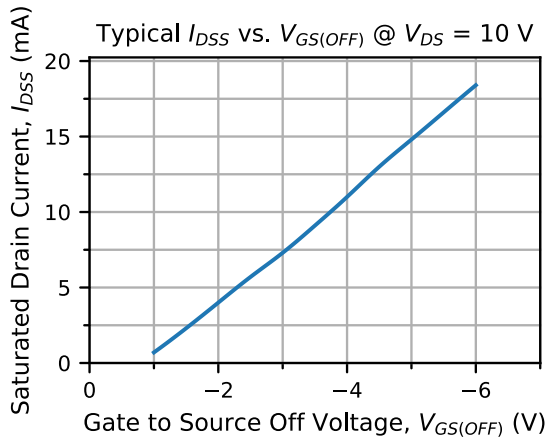
Static Characteristics (@ $T_A = 25^\circ\text{C}$, Unless otherwise specified)

Parameters	Conditions	2N3458		Unit
		Min	Max	
$V_{(BR)GSS}$ Gate to Source Breakdown Voltage	$V_{DS} = 0V, I_G = -1\mu A$	-50		V
I_{GSS} Gate to Source Reverse Current	$V_{GS} = -30V, V_{DS} = 0V$		-250	pA
$V_{GS(OFF)}$ Gate to Source Cutoff Voltage	$V_{DS} = 20V, I_D = 1nA$		-7.8	V
I_{DSS} Drain to Source Saturation Current	$V_{DS} = 20V, V_{GS} = 0V$ (Pulsed)	3	15	mA

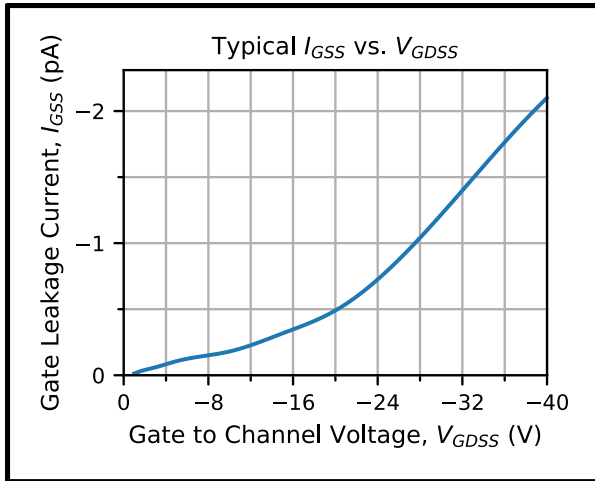
Dynamic Characteristics (@ $T_A = 25^\circ\text{C}$, Unless otherwise specified)

Parameters	Conditions	2N3458		Unit
		Min	Max	
G_{FS} Forward Transconductance	$V_{DS} = -20V, V_{GS} = 0V, f = 1kHz$	2.5	10	mS
C_{iss} Input Capacitance	$V_{DS} = 0V, V_{GS} = (), f = 1MHz$		18 (10)	pF V
C_{rss} Reverse Transfer Capacitance	$V_{DS} = 30V, I_D = 5mA, f = 1MHz$		5	pF

Typical 2N3458 Characteristics

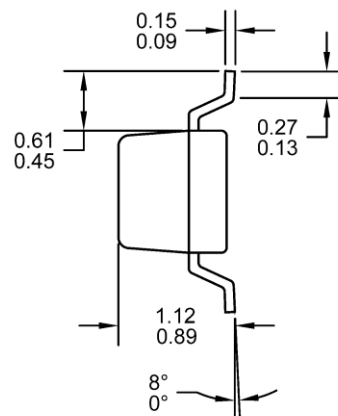
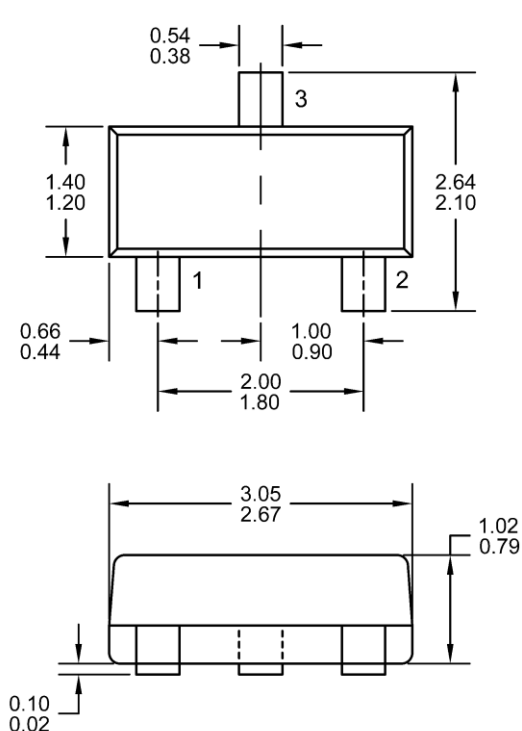


Typical 2N3458 Characteristics (Continued)



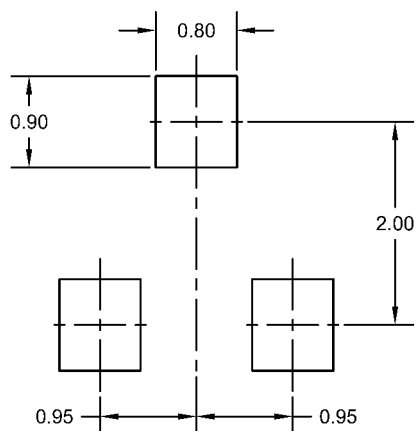
SOT23 (TO-236AB) Mechanical and Layout Data

Package Outline Data



1. All linear dimensions are in millimeters.
2. Package weight approximately 0.12 grams
3. Molded plastic case UL 94V-0 rated
4. For Tape and Reel specifications refer to InterFET CTC-021 Tape and Reel Specification, Document number: IF39002
5. Bulk product is shipped in standard ESD shipping material
6. Refer to JEDEC standards for additional information.

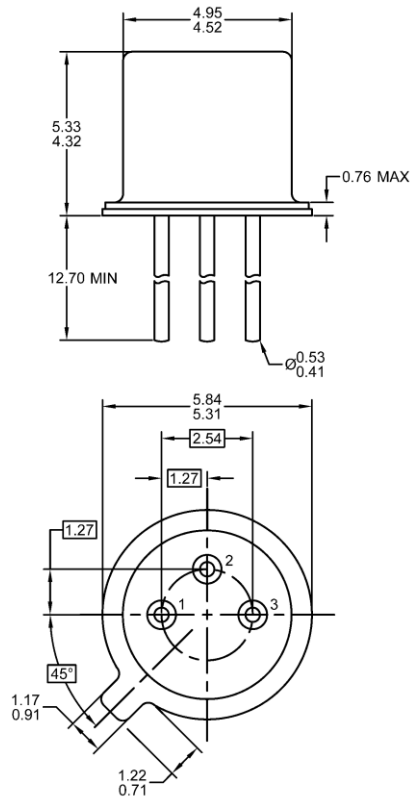
Suggested Pad Layout



1. All linear dimensions are in millimeters.
2. The suggested land pattern dimensions have been provided for reference only. A more robust pattern may be desired for wave soldering.

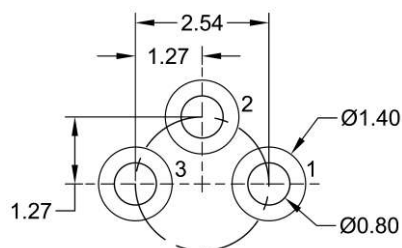
T0-18 Mechanical and Layout Data

Package Outline Data



1. All linear dimensions are in millimeters.
2. Package weight approximately 0.29 grams
3. Bulk product is shipped in standard ESD shipping material
4. Refer to JEDEC standards for additional information.

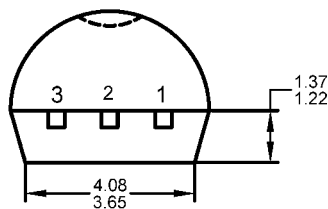
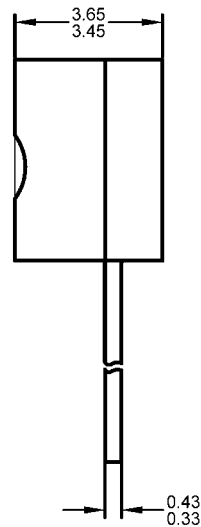
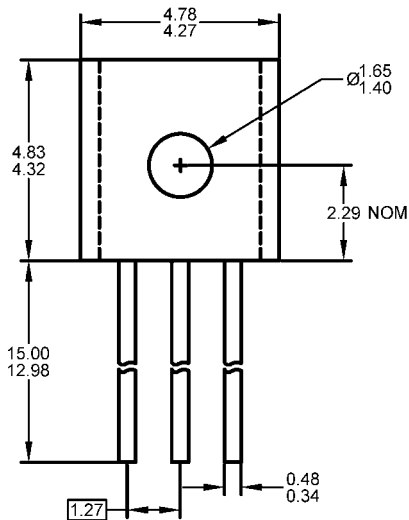
Suggested Through-Hole Layout



1. All linear dimensions are in millimeters.
2. The suggested land pattern dimensions have been provided as a straight lead reference only. A more robust pattern may be desired for wave soldering and/or bent lead configurations.

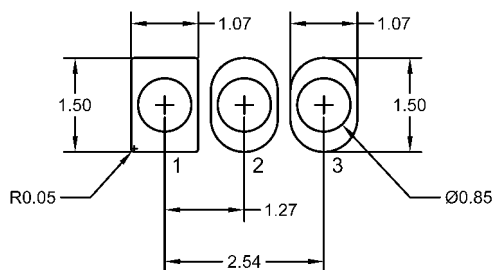
TO-92 Mechanical and Layout Data

Package Outline Data



1. All linear dimensions are in millimeters.
2. Package weight approximately 0.19 grams
3. Molded plastic case UL 94V-0 rated
4. Bulk product is shipped in standard ESD shipping material
5. Refer to JEDEC standards for additional information.

Suggested Through-Hole Layout



1. All linear dimensions are in millimeters.
2. The suggested land pattern dimensions have been provided as a straight lead reference only. A more robust pattern may be desired for wave soldering and/or bent lead configurations.

Compliance and Legal

Environment

InterFET parts follow the latest RoHS Compliance, REACH Compliance, Proposition 65 Statement, TSCA Statement, and Chemical Disposal and Waste Mitigation requirement and guidelines. For more on InterFET's Environmental Commitment please visit

www.InterFET.com/environmental/.

Package materials

Parameters	SOT23	SOIC8	TO-92	Metal Case
Alloy	CDA194	C194 1/2H	C194 1/2H	Kovar
Cu	Balance	97% min	97% min	
Fe	2.1 – 2.6%	2.1 – 2.6%	2.1 – 2.6%	53%
Zn	0.05 – 0.2%	0.05 – 0.2%	0.05 – 0.15%	
P	0.015 – 0.15%	0.015 – 0.15%	0.015 – 0.15%	
Pb	0.03% max	0.03% max	0.03% max	
Ni				29%
Co				17%
Mn				0.3%
Si				0.2%
C				<0.01%
Au				Plating

Package tests

Parameters	SOT23	SOIC8	TO-92	Metal Case
MSL	Level 1	TBD	N/A	N/A
ESD	Class M4 Machine Model Class 3A HBM	Class M4 Machine Model Class 3A HBM	Class M4 Machine Model Class 3A HBM	Class M4 Machine Model Class 3A HBM

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